

# Precision Reference with Low Offset Error Amplifier

## FEATURES

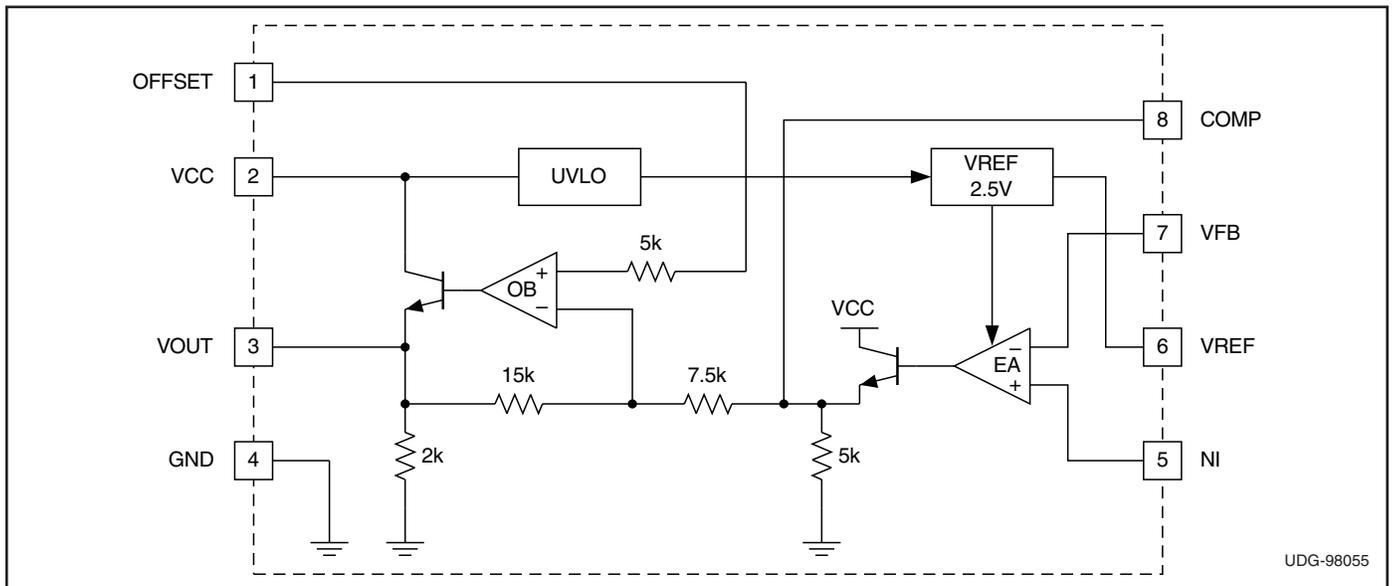
- Accessible 2.5V Precision Reference
- 0.4% Initial Reference Accuracy
- 1% Reference Accuracy over Line, Load, and Full Temperature Range
- Low 1mV Offset Error Amplifier
- Supports Closed Loop Soft Start
- 2X Inverting Amplifier / Buffer Output
- 4.1V Undervoltage Lockout
- ICC 2mA at 5V
- 8-Pin SOIC or DIL Package

## DESCRIPTION

The UC3965 is suitable for applications needing greater precision and more functionality than the TL431 type shunt regulators. The wide range VCC input capability enables the device to be biased from the secondary side output voltage rail, resulting in closed loop soft start.

The UC3965 includes an accessible 2.5V precision reference which offers 0.4% initial and 1% reference accuracy over line, load, and full temperature range with a low offset error amplifier, a 2X inverting amplifier/buffer, and an undervoltage lockout circuit. The IC is ideally suited for applications where high precision PWM power supply regulation is required. Typically, the error amplifier is configured to compare a fraction of the to be regulated power supply voltage to the on-chip 2.5V reference. The 2X amplifier/buffer output is then used to drive a PWM controller or regulator. The UC3965 is also capable of driving an optocoupler diode for isolated applications.

## BLOCK DIAGRAM



### ABSOLUTE MAXIMUM RATINGS

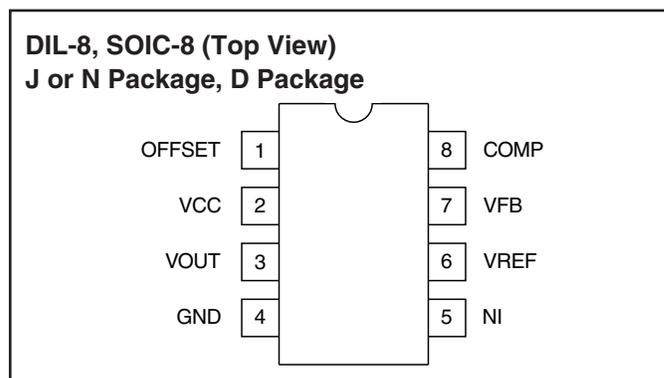
VCC	-0.3V to 20V
VREF	-0.3V to 6V
VFB, COMP, NI, VOUT	-0.3V TO 6V
Storage Temperature	-65°C to +150°C
Junction Temperature	-55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

*Currents are positive into, negative out of the specified terminal. All voltages are with respect to ground. Consult Packaging Section of Databook for thermal limitations and considerations of packages.*

### ORDERING INFORMATION

	TEMPERATURE RANGE	PACKAGE
UC1965J	-55°C to +125°C	CDIP
UC2965D	-40°C to +85°C	SOIC
UC2965N		PDIP
UC3965D	0°C to +70°C	SOIC
UC3965N		PDIP

### CONNECTION DIAGRAM



### ELECTRICAL CHARACTERISTICS

Unless otherwise specified, VCC = 5V, TA = TJ.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>General</b>					
VCC		4.3		20	V
Operating Current	VCC = 5V	1.5	2	4	mA
Undervoltage Current				200	μA
Minimum Voltage to Start		3.9	4.1	4.3	V
Hysteresis		200	300	400	mV
<b>VREF</b>					
VREF Initial Accuracy	+25°C	2.49	2.5	2.51	V
VREF Over Temperature	-55°C to +125°C	2.48	2.5	2.52	V
Total Output Variation	Line, Load, Temperature	2.475	2.5	2.525	V
Line Regulation	VCC = 4.3V to 20V		2	10	mV
Load Regulation	0μA to 500μA		2	10	mV
Short Circuit Current	VREF = 0V		2		mA
<b>Error Amplifier</b>					
Input Bias	VCM = 2.5V		200	400	nA
Input Offset Voltage	VCM = 2.5V		1	2	mV
Input Offset Current	VCM = 2.5V	-100	0	100	nA
Gain Bandwidth Product	VIN = 50mV P-P (Note 1)		6		MHz
Open Loop Gain	VOUT = 1V to 3.75V	80	100		dB

**ELECTRICAL CHARACTERISTICS** Unless otherwise specified,  $V_{CC} = 5V$ ,  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Error Amplifier Section (cont.)</b>					
Output Low Level	$I_{OUT} = 0\mu A$		0.8		V
	$I_{OUT} = 100\mu A$		1.2		V
Output High Level	$I_{OUT} = 0\mu A$		4		V
	$I_{OUT} = -500\mu A$		4		V
Short Circuit Current	$V_{COMP} = 0V$		8		mA
CMRR	$V_{CM} = 1.25V$ to $3.75V$	70	100		dB
PSRR	$V_{CC} = 4.3V$ to $20V$	70	100		dB
Rising Slew Rate			2		V/ $\mu s$
Falling Slew Rate			0.4		V/ $\mu s$
<b>Inverting Buffer Amplifier</b>					
Input Bias	$V_{CM} = 2.5V$		1	2	$\mu A$
Output Offset Voltage	$V_{CM} = 2.5V$	-20	0	20	mV
Gain Bandwidth Product	$V_{IN} = 50mV$ P-P (Note 1)		1.5		MHz
Closed Loop Gain	Inverting Gain	-2.04	-2	-1.96	V/V
Output Low Level	$I_{OUT} = 0\mu A$		0.3		V
	$I_{OUT} = 100\mu A$		0.5		V
Output High Level	$I_{OUT} = 0mA$		4		V
	$I_{OUT} = -4mA$		4		V
Short Circuit Current	$V_{OUT} = 0V$		18		mA
CMRR	$V_{CM} = 1.25V$ to $3.75V$	70	100		dB
PSRR	$V_{CC} = 4.3V$ to $20V$	70	100		dB
Rising Slew Rate			0.9		V/ $\mu s$
Falling Slew Rate			0.9		V/ $\mu s$

Note 1: Guaranteed by design. Not 100% tested in production.

**PIN DESCRIPTIONS**

**COMP:** The output of the error amplifier and the input to the inverting terminal of the internal output buffer. This pin is available to compensate the high frequency gain of the error amplifier.

**GND:** The reference and power ground for the device.

**NI:** The non-inverting input to the error amplifier.

**OFFSET:** The non-inverting input to the internal output buffer.

**VCC:** The power input to the device. The minimum to maximum operating voltage is 4.3V to 20V.

**VFB:** The inverting terminal of the error amplifier used as both the voltage sense input to the error amplifier and its other compensation point.

**VOUT:** The emitter of the output transistor. This pin is the output of the inverting buffer. This pin has the capability to drive an optocoupler or a PWM controller directly.

**VREF:** The output of the trimmed precision reference. This reference maintains within 1% of its initial value over its entire line, load, and temperature range.

## APPLICATION INFORMATION

For designs requiring input-output isolation, the UC3965 is used in secondary side output voltage sensing. As shown in Fig. 1, the precision reference and low offset error amplifier can be used in converters, such as the isolated flyback, where the primary side error amplifier is not used or simply not present. In this case, the UCC3809 is used as the primary side controller.

The precision reference of the UC3965 is tied to the non-inverting input of the device's internal error amplifier. The output voltage of the converter is resistively divided and compared to this reference at the inverting input. This error amplifier has a low 1mV input offset voltage

that insures accurate regulation of the output. The internal error amplifier drives the inverting input of the output buffer (OB) which drives an optocoupler diode. The wide range VCC voltage enables the device to be biased from the secondary side output voltage rail, resulting in closed loop soft start.

As the output voltage increases beyond its desired value, the voltage difference at the error amplifier increases. This results in less drive at the inverting input of the internal buffer, increasing its output drive to the optocoupler. If the application does not require input-output isolation, this buffer could be used to drive the PWM directly.

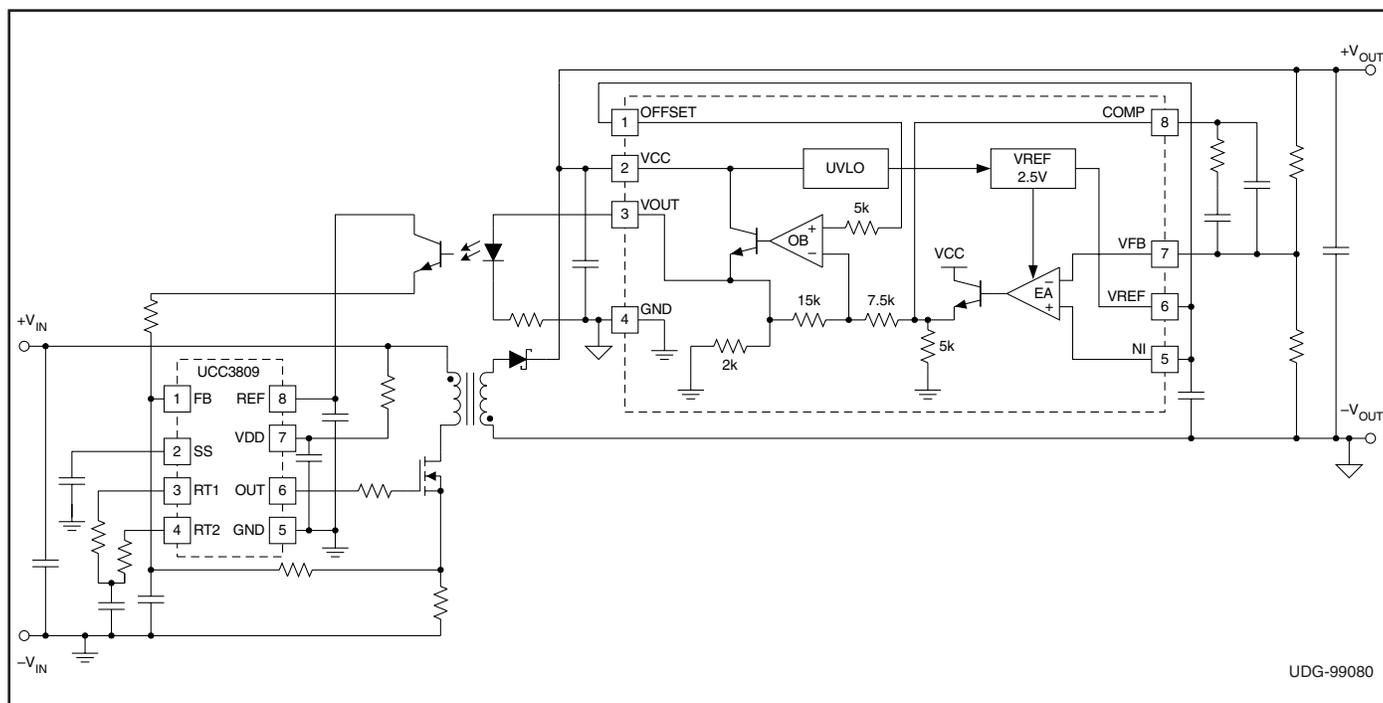


Figure 1. Typical application diagram.

## ADDITIONAL INFORMATION

For additional application information biasing the UC3965, please refer to the following publication:

[1] Application Note U-165, *Design Review: Isolated 50W Flyback with the UCC3809 Primary Side Controller and the UC3965 Precision Reference and Error Amplifier*, by Lisa Dinwoodie.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UC2965D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
UC2965DTR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
UC3965D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
UC3965DTR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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